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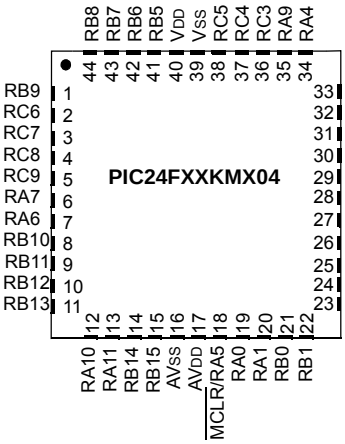
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16km102-i-ss

Pin Diagrams (Continued)

44-Pin TQFP/QFN(1)



Pin	Pin Features	
	PIC24FXXKMX04	PIC24FVXXKMX04
1	AN21/SDA1/T1CK/U1RTS/U1BCLK/IC2/ /CLC1O/CTED4/CN21/RB9	
2	U1RX/ /CN18/RC6	
3	U1TX/ /CN17/RC7	
4	/CN20/RC8	
5	IC4/OC2F/CTED7/CN19/RC9	
6	IC1/ / /CTED3/CN9/RA7	
7	/OC1A/CTED1/INT2/CN8/RA6	VCAP or VDDCORE
8	PGED2/SDI1/OC1C/CTED11/CN16/RB10	
9	PGEC2/SCK1/OC2A/CTED9/CN15/RB11	
10	/AN12/HLVDIN/ /CTED2/ CN14/RB12	/AN12/HLVDIN/ /CTED2/INT2/ CN14/RB12
11	/ /AN11/SDO1/OC1D/CTPLS/CN13/RB13	
12	/ /CN35/RA10	
13	/ /CTED8/CN36/RA11	
14	/CVREF/ / /AN10/ / /C1OUT/OCFA/CTED5/INT1/CN12/ RB14	
15	/ /AN9/ /REFO/SS1/TCKIA/CTED6/CN11/RB15	
16	AVSS	
17	AVDD	
18	MCLR/VPP/RA5	
19	CVREF+/VREF+/ /AN0/ /CN2/ RA0	CVREF+/VREF+/ /AN0/ / CTED1/CN2/RA0
20	CVREF-/VREF-/AN1/CN3/RA1	
21	PGED1/AN2/CTCMP/ULPWU/C1IND/ / / /CN4/RB0	
22	PGEC1/ / /AN3/C1INC/ / /CTED12/CN5//RB1	
23	/ /AN4/C1INB/ / /TCKIB/CTED13/CN6/RB2	
24	/AN5/C1INA/ / /CN7/RB3	
25	AN6/CN32/RC0	
26	AN7/CN31/RC1	
27	AN8/CN10/RC2	
28	VDD	
29	VSS	
30	OSCI/CLKI/AN13/CN30/RA2	
31	OSCO/CLKO/AN14/CN29/RA3	
32	OCFB/CN33/RA8	
33	SOSCI/AN15/ / /CN1/RB4	
34	SOSCO/SCLKI/AN16/PWRLCLK/ /CN0/RA4	
35	/CN34/RA9	
36	/CN28/RC3	
37	/CN25/RC4	
38	/CN26/RC5	
39	VSS	
40	VDD	
41	PGED3/AN17/ASDA1/OC1E/CLCINA/CN27/RB5	
42	PGEC3/AN18/ASCL1/OC1F/CLCINB/CN24/RB6	
43	AN19/INT0/CN23/RB7	AN19/ /OC1A/INT0/CN23/RB7
44	AN20/SCL1/U1CTS/C3OUT/OC1B/CTED10/CN22/RB8	

Legend: Values in indicate pin function differences between PIC24F(V)XXKM202 and PIC24F(V)XXKM102 devices.

Note 1: Exposed pad on underside of device is connected to VSS.

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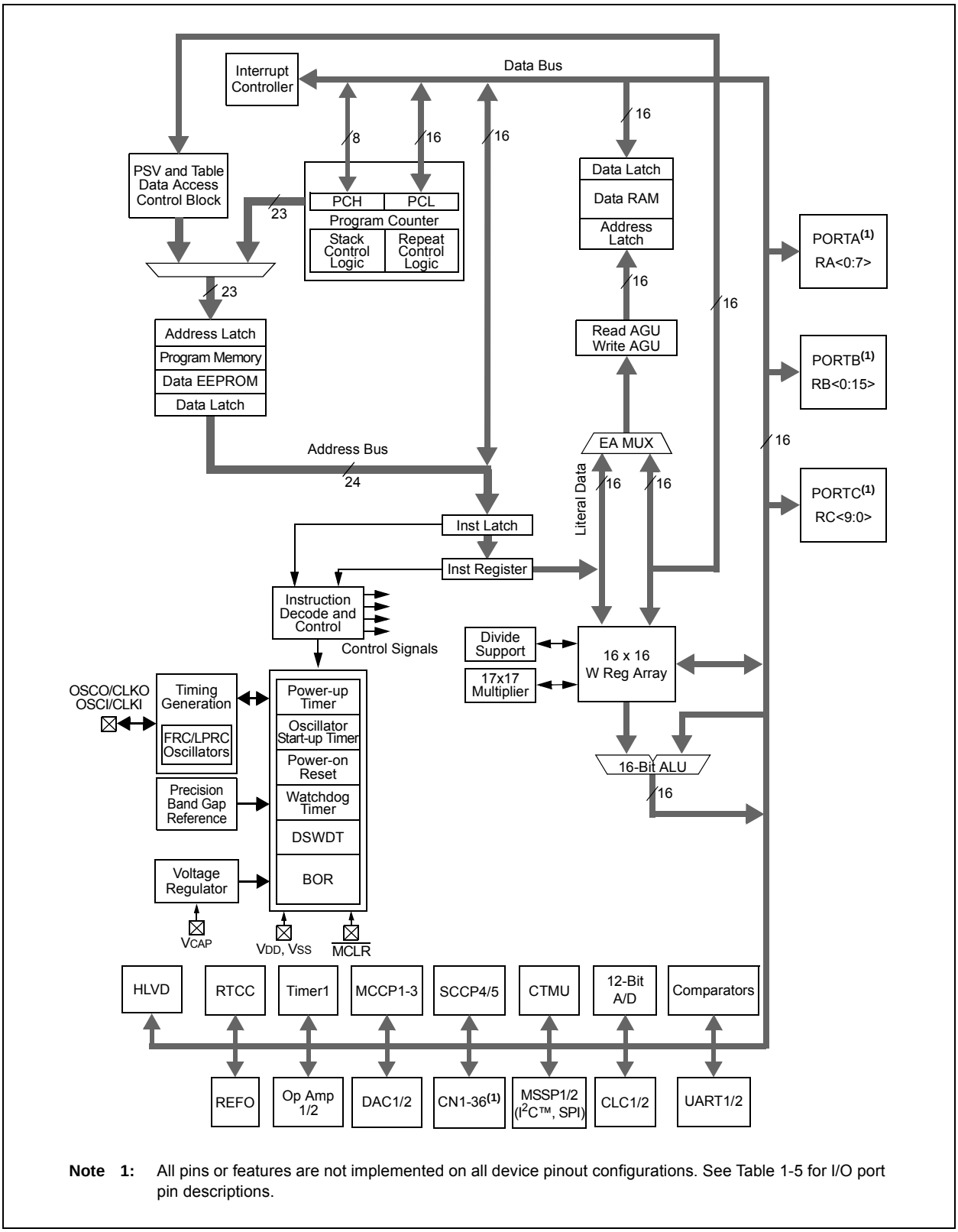
FIGURE 1-1: PIC24FXXXXX FAMILY GENERAL BLOCK DIAGRAMS



Note 1: All pins or features are not implemented on all device pinout configurations. See Table 1-5 for I/O port pin descriptions.

TABLE 4-24: PAD CONFIGURATION REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PADCFG1	2FCh	—	—	—	—	SDO2DIS(1)	SCK2DIS(1)	SDO1DIS	SCK1DIS	—	—	—	—	—	—	—	—	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: These bits are not available on the PIC24F(V)08KM101 device, read as '0'.

REGISTER 5-1: NVMCON: FLASH MEMORY CONTROL REGISTER

R/SO-0, HC	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	PGMONLY(4)	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ERASE	NVMOP5(1)	NVMOP4(1)	NVMOP3(1)	NVMOP2(1)	NVMOP1(1)	NVMOP0(1)
bit 7							bit 0

Legend:	SO = Settable Only bit	HC = Hardware Clearable bit	
-n = Value at POR	'1' = Bit is set	R = Readable bit	W = Writable bit
'0' = Bit is cleared	x = Bit is unknown	U = Unimplemented bit, read as '0'	

bit 15 **WR:** Write Control bit
- 1 = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
- 0 = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit
- 1 = Enables Flash program/erase operations
- 0 = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit
- 1 = An improper program or erase sequence attempt, or termination has occurred (bit is set automatically on any set attempt of the WR bit)
- 0 = The program or erase operation completed normally

bit 12 **PGMONLY:** Program Only Enable bit(4)

bit 11-7 **Unimplemented:** Read as '0'

bit 6 **ERASE:** Erase/Program Enable bit
- 1 = Performs the erase operation specified by the NVMOP<5:0> bits on the next WR command
- 0 = Performs the program operation specified by the NVMOP<5:0> bits on the next WR command

bit 5-0 **NVMOP<5:0>:** Programming Operation Command Byte bits(1)

Erase Operations (when ERASE bit is '1'):
- 1010xx = Erase entire boot block (including code-protected boot block)(2)
- 1001xx = Erase entire memory (including boot block, configuration block, general block)(2)
- 011010 = Erase 4 rows of Flash memory(3)
- 011001 = Erase 2 rows of Flash memory(3)
- 011000 = Erase 1 row of Flash memory(3)
- 0101xx = Erase entire configuration block (except code protection bits)
- 0100xx = Erase entire data EEPROM(4)
- 0011xx = Erase entire general memory block programming operations
- 0001xx = Write 1 row of Flash memory (when ERASE bit is '0')(3)

Note 1: All other combinations of NVMOP<5:0> are no operation.

2: Available in ICSP™ mode only. Refer to the device programming specification.

3: The address in the Table Pointer decides which rows will be erased.

4: This bit is used only while accessing data EEPROM.

REGISTER 8-31: IPC18: INTERRUPT PRIORITY CONTROL REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	HLVDIP2	HLVDIP1	HLVDIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2-0 **HLVDIP<2:0>:** High/Low-Voltage Detect Interrupt Priority bits

111 = Interrupt is Priority 7 (highest priority interrupt)

•

•

•

001 = Interrupt is Priority 1

000 = Interrupt source is disabled

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7 **CLKLOCK:** Clock Selection Lock Enable bit
If FSCM is Enabled (FCKSM1 = 1):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit
If FSCM is Disabled (FCKSM1 = 0):
Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.

bit 6 **Unimplemented:** Read as '0'

bit 5 **LOCK:** PLL Lock Status bit(2)
1 = PLL module is in lock or PLL module start-up timer is satisfied
0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit
1 = FSCM has detected a clock failure
0 = No clock failure has been detected

bit 2 **SOSCDRV**: Secondary Oscillator Drive Strength bit(3)
1 = High-power SOSC circuit is selected
0 = Low/high-power select is done via the SOSCSRC Configuration bit

bit 1 **SOSCEN:** 32 kHz Secondary Oscillator (SOSC) Enable bit
1 = Enables the Secondary Oscillator
0 = Disables the Secondary Oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Initiates an oscillator switch to the clock source specified by the NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Reset values for these bits are determined by the FNOSCx Configuration bits.
2: This bit also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.
3: When SOSC is selected to run from a digital clock input, rather than an external crystal (SOSCSRC = 0), this bit has no effect.

13.4 Input Capture Mode

Input Capture mode is used to capture a timer value from an independent timer base upon an event on an input pin or other internal Trigger source. The input capture features are useful in applications requiring frequency (time period) and pulse measurement. Figure 13-6 depicts a simplified block diagram of Input Capture mode.

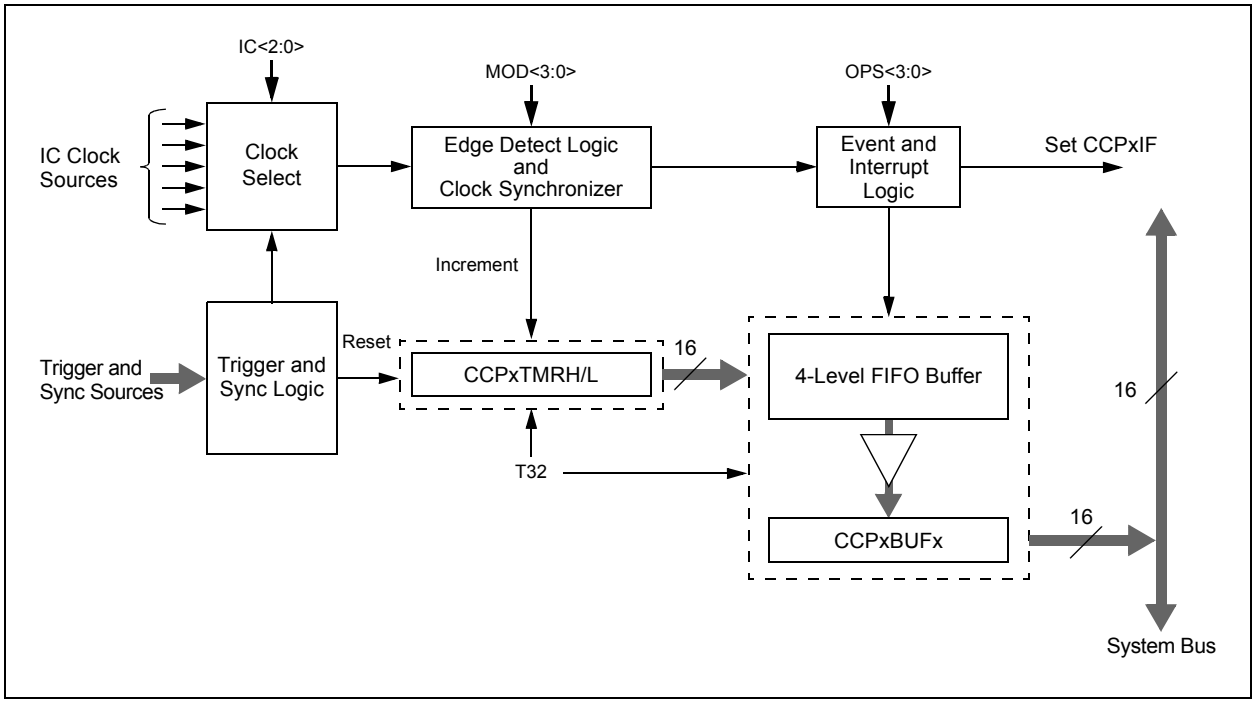
Input Capture mode uses a dedicated 16/32-bit, synchronous, up counting timer for the capture function. The timer value is written to the FIFO when a capture event occurs. The internal value may be read (with a synchronization delay) using the CCPxTMRH/L register.

To use Input Capture mode, the CCSEL bit (CCPxCON1L<4>) must be set. The T32 and the MOD<3:0> bits are used to select the proper Capture mode, as shown in Table 13-4.

TABLE 13-4: INPUT CAPTURE MODES

MOD<3:0> (CCPxCON1L<3:0>)	T32 (CCPxCON1L<5>)	Operating Mode
0000	0	Edge Detect (16-bit capture)
0000	1	Edge Detect (32-bit capture)
0001	0	Every Rising (16-bit capture)
0001	1	Every Rising (32-bit capture)
0010	0	Every Falling (16-bit capture)
0010	1	Every Falling (32-bit capture)
0011	0	Every Rise/Fall (16-bit capture)
0011	1	Every Rise/Fall (32-bit capture)
0100	0	Every 4th Rising (16-bit capture)
0100	1	Every 4th Rising (32-bit capture)
0101	0	Every 16th Rising (16-bit capture)
0101	1	Every 16th Rising (32-bit capture)

FIGURE 13-6: INPUT CAPTURE x BLOCK DIAGRAM



REGISTER 16-10: ALMINSEC: ALARM MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0
bit 15							bit 8

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **MINTEN<2:0>:** Binary Coded Decimal Value of Minute’s Tens Digit bits
Contains a value from 0 to 5.

bit 11-8 **MINONE<3:0>:** Binary Coded Decimal Value of Minute’s Ones Digit bits
Contains a value from 0 to 9.

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SECTEN<2:0>:** Binary Coded Decimal Value of Second’s Tens Digit bits
Contains a value from 0 to 5.

bit 3-0 **SECONE<3:0>:** Binary Coded Decimal Value of Second’s Ones Digit bits
Contains a value from 0 to 9.

16.3 Calibration

The real-time crystal input can be calibrated using the periodic auto-adjust feature. When properly calibrated, the RTCC can provide an error of less than 3 seconds per month. This is accomplished by finding the number of error clock pulses and storing the value into the lower half of the RCFGCAL register. The 8-bit signed value, loaded into the lower half of RCFGCAL, is multiplied by four and will be either added or subtracted from the RTCC timer, once every minute. Refer to the steps below for RTCC calibration:

1. Using another timer resource on the device, the user must find the error of the 32.768 kHz crystal.
2. Once the error is known, it must be converted to the number of error clock pulses per minute.
3. a) If the oscillator is faster than ideal (negative result from Step 2), the RCFGCAL register value must be negative. This causes the specified number of clock pulses to be subtracted from the timer counter, once every minute.

   b) If the oscillator is slower than ideal (positive result from Step 2), the RCFGCAL register value must be positive. This causes the specified number of clock pulses to be subtracted from the timer counter, once every minute.

EQUATION 16-1:

(Ideal Frequency† – Measured Frequency) *
60 = Clocks per Minute

† Ideal Frequency = 32,768 Hz

Writes to the lower half of the RCFGCAL register should only occur when the timer is turned off, or immediately after the rising edge of the seconds pulse, except when SECONDS = 00, 15, 30 or 45. This is due to the auto-adjust of the RTCC at 15 second intervals.

Note:	It is up to the user to include, in the error value, the initial error of the crystal: drift due to temperature and drift due to crystal aging.

16.4 Alarm

- Configurable from half second to one year
- Enabled using the ALRMEN bit (ALCFGRPT<15>)
- One-time alarm and repeat alarm options are available

16.4.1 CONFIGURING THE ALARM

The alarm feature is enabled using the ALRMEN bit. This bit is cleared when an alarm is issued. Writes to ALRMVAL should only take place when ALRMEN = 0.

As shown in Figure 16-2, the interval selection of the alarm is configured through the AMASKx bits (ALCFGRPT<13:10>). These bits determine which and how many digits of the alarm must match the clock value for the alarm to occur.

The alarm can also be configured to repeat based on a preconfigured interval. The amount of times this occurs, once the alarm is enabled, is stored in the ARPT<7:0> bits (ALCFGRPT<7:0>). When the value of the ARPTx bits equals 00h and the CHIME bit (ALCFGRPT<14>) is cleared, the repeat function is disabled, and only a single alarm will occur. The alarm can be repeated up to 255 times by loading ARPT<7:0> with FFh.

After each alarm is issued, the value of the ARPTx bits is decremented by one. Once the value has reached 00h, the alarm will be issued one last time, after which, the ALRMEN bit will be cleared automatically and the alarm will turn off.

Indefinite repetition of the alarm can occur if the CHIME bit = 1. Instead of the alarm being disabled when the value of the ARPTx bits reaches 00h, it rolls over to FFh and continues counting indefinitely while CHIME is set.

16.4.2 ALARM INTERRUPT

At every alarm event, an interrupt is generated. In addition, an alarm pulse output is provided that operates at half the frequency of the alarm. This output is completely synchronous to the RTCC clock and can be used as a Trigger clock to other peripherals.

Note:	Changing any of the registers, other than the RCFGCAL and ALCFGRPT registers, and the CHIME bit while the alarm is enabled (ALRMEN = 1), can result in a false alarm event leading to a false alarm interrupt. To avoid a false alarm event, the timer and alarm values should only be changed while the alarm is disabled (ALRMEN = 0). It is recommended that the ALCFGRPT register and CHIME bit be changed when RTCSYNC = 0.

REGISTER 19-1: AD1CON1: A/DA/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	—	—	MODE12	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
SSRC3	SSRC2	SSRC1	SSRC0	—	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** A/D Operating Mode bit
1 = A/D Converter is operating
0 = A/D Converter is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** A/D Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **MODE12:** 12-Bit A/D Operation Mode bit
1 = 12-bit A/D operation
0 = 10-bit A/D operation

bit 9-8 **FORM<1:0>:** Data Output Format bits (see the following formats)
11 = Fractional result, signed, left justified
10 = Absolute fractional result, unsigned, left justified
01 = Decimal result, signed, right justified
00 = Absolute decimal result, unsigned, right justified

bit 7-4 **SSRC<3:0>:** Sample Clock Source Select bits
1111 = Reserved
•
•
•
1101 = Reserved
1100 = CLC2 event ends sampling and starts conversion
1011 = SCCP4 Compare Event (CCP4IF) ends sampling and starts conversion
1010 = MCCP3 Compare Event (CCP3IF) ends sampling and starts conversion
1001 = MCCP2 Compare Event (CCP2IF) ends sampling and starts conversion
1000 = CLC1 event ends sampling and starts conversion
0111 = Internal counter ends sampling and starts conversion (auto-convert)
0110 = TMR1 Sleep mode Trigger event ends sampling and starts conversion(1)
0101 = TMR1 event ends sampling and starts conversion
0100 = CTMU event ends sampling and starts conversion
0011 = SCCP5 Compare Event (CCP5IF) ends sampling and starts conversion
0010 = MCCP1 Compare Event (CCP1IF) ends sampling and starts conversion
0001 = INT0 event ends sampling and starts conversion
0000 = Clearing the Sample bit ends sampling and starts conversion

Note 1: This version of the TMR1 Trigger allows A/D conversions to be triggered from TMR1 while the device is operating in Sleep mode. The SSRC<3:0> = 0101 option allows conversions to be triggered in Run or Idle modes only.

REGISTER 19-4: AD1CON5: A/D CONTROL REGISTER 5

R/W-0	R/W-0	R/W-0	R/W-0	r-0	U-0	R/W-0	R/W-0
ASEN(1)	LPEN	CTMREQ	BGREQ	r	—	ASINT1	ASINT0
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	WM1	WM0	CM1	CM0
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ASEN:** A/D Auto-Scan Enable bit(1)
- 1 = Auto-scan is enabled
- 0 = Auto-scan is disabled

bit 14 **LPEN:** A/D Low-Power Enable bit
- 1 = Returns to Low-Power mode after scan
- 0 = Remains in Full-Power mode after scan

bit 13 **CTMREQ:** CTMU Request bit
- 1 = CTMU is enabled when the A/D is enabled and active
- 0 = CTMU is not enabled by the A/D

bit 12 **BGREQ:** Band Gap Request bit
- 1 = Band gap is enabled when the A/D is enabled and active
- 0 = Band gap is not enabled by the A/D

bit 11 **Reserved:** Maintain as '0'

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **ASINT<1:0>:** Auto-Scan (Threshold Detect) Interrupt Mode bits
- 11 = Interrupt after a Threshold Detect sequence has completed and a valid compare has occurred
- 10 = Interrupt after a valid compare has occurred
- 01 = Interrupt after a Threshold Detect sequence has completed
- 00 = No interrupt

bit 7-4 **Unimplemented:** Read as '0'

bit 3-2 **WM<1:0>:** A/D Write Mode bits
- 11 = Reserved
- 10 = Auto-compare only (conversion results are not saved, but interrupts are generated when a valid match, as defined by the CMx and ASINTx bits, occurs)
- 01 = Convert and save (conversion results are saved to locations as determined by the register bits when a match, as defined by the CMx bits, occurs)
- 00 = Legacy operation (conversion data is saved to a location determined by the buffer register bits)

bit 1-0 **CM<1:0>:** A/D Compare Mode bits
- 11 = Outside Window mode (valid match occurs if the conversion result is outside of the window defined by the corresponding buffer pair)
- 10 = Inside Window mode (valid match occurs if the conversion result is inside the window defined by the corresponding buffer pair)
- 01 = Greater Than mode (valid match occurs if the result is greater than the value in the corresponding buffer register)
- 00 = Less Than mode (valid match occurs if the result is less than the value in the corresponding buffer register)

Note 1: When using auto-scan with Threshold Detect (ASEN = 1), do not configure the sample clock source to Auto-Convert mode (SSRC<3:0> = 7). Any other available SSRC selection is valid. To use auto-convert as the sample clock source (SSRC<3:0> = 7), make sure ASEN is cleared.

NOTES:

TABLE 27-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX) 2.0V to 5.5V (PIC24FV16KMXXX) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical**	**Max**	**Units**	**Conditions**	
IDD Current						
D20	PIC24FV16KMXXX	269	450	µA	2.0V	0.5 MIPS, FOSC = 1 MHz(1)
		465	830	µA	5.0V	
	PIC24F16KMXXX	200	330	µA	1.8V	
		410	750	µA	3.3V	
DC22	PIC24FV16KMXXX	490	—	µA	2.0V	1 MIPS, FOSC = 2 MHz(1)
		880	—	µA	5.0V	
	PIC24F16KMXXX	407	—	µA	1.8V	
		800	—	µA	3.3V	
DC24	PIC24FV16KMXXX	13.0	15.0	mA	5.0V	16 MIPS, FOSC = 32 MHz(1)
	PIC24F16KMXXX	12.0	13.0	mA	3.3V	
DC26	PIC24FV16KMXXX	2.0	—	mA	2.0V	FRC (4 MIPS), FOSC = 8 MHz
		3.5	—	mA	5.0V	
	PIC24F16KMXXX	1.80	—	mA	1.8V	
		3.40	—	mA	3.3V	
DC30	PIC24FV16KMXXX	48.0	250	µA	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
		75.0	275	µA	5.0V	
	PIC24F16KMXXX	8.1	28.0	µA	1.8V	
		13.50	55.00	µA	3.3V	

Legend: Unshaded rows represent PIC24F16KMXXX devices and shaded rows represent PIC24FV16KMXXX devices.

Note 1: The oscillator is in External Clock mode (FOSCSEL<2:0> = 010, FOSC<1:0> = 00).

TABLE 27-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD}) (CONTINUED)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical(1)**	**Max**	**Units**	**Conditions**	
Module Differential Current (ΔI_{PD})(3)						
DC71	PIC24FV16KMXXX	0.50	—	µA	2.0V	Watchdog Timer Current: ΔWDT
		0.70	1.5	µA	5.0V	
	PIC24F16KMXXX	0.50	—	µA	1.8V	
		0.70	1.5	µA	3.3V	
DC72	PIC24FV16KMXXX	0.80	—	µA	2.0V	32 kHz Crystal with RTCC, DSWDT or Timer1: ΔSOSC (SOSCSEL = 0)
		1.50	2.0	µA	5.0V	
	PIC24F16KMXXX	0.70	—	µA	1.8V	
		1.0	1.5	µA	3.3V	
DC75	PIC24FV16KMXXX	5.4	—	µA	2.0V	ΔHLVD
		8.1	14.0	µA	5.0V	
	PIC24F16KMXXX	4.9	—	µA	1.8V	
		7.5	14.0	µA	3.3V	
DC76	PIC24FV16KMXXX	5.6	—	µA	2.0V	ΔBOR
		6.5	11.2	µA	5.0V	
	PIC24F16KMXXX	5.6	—	µA	1.8V	
		6.0	11.2	µA	3.3V	
DC78	PIC24FV16KMXXX	0.03	—	µA	2.0V	Low-Power BOR: ΔLPBOR
		0.05	0.3	µA	5.0V	
	PIC24F16KMXXX	0.03	—	µA	1.8V	
		0.05	0.3	µA	3.3V	

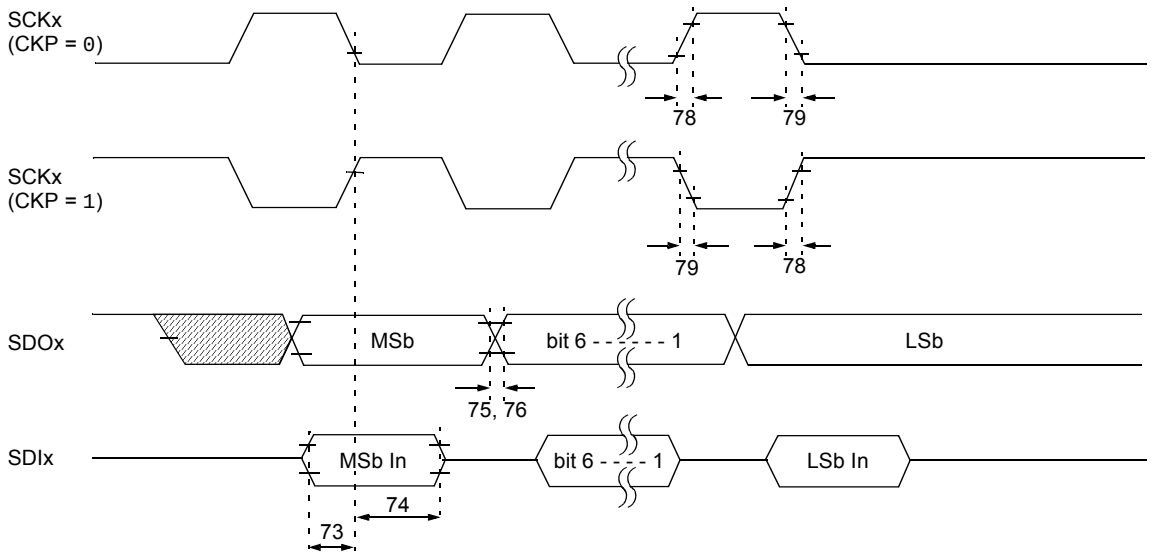
Legend: Unshaded rows represent PIC24F16KMXXX devices and shaded rows represent PIC24FV16KMXXX devices.

Note 1: Data in the Typical column is at 3.3V, +25°C (PIC24F16KMXXX) or 5.0V, +25°C (PIC24FV16KMXXX) unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as outputs and set low. PMSLP is set to '0' and WDT, etc., are all switched off.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

FIGURE 27-11: EXAMPLE SPI MASTER MODE TIMING (CKE = 0)

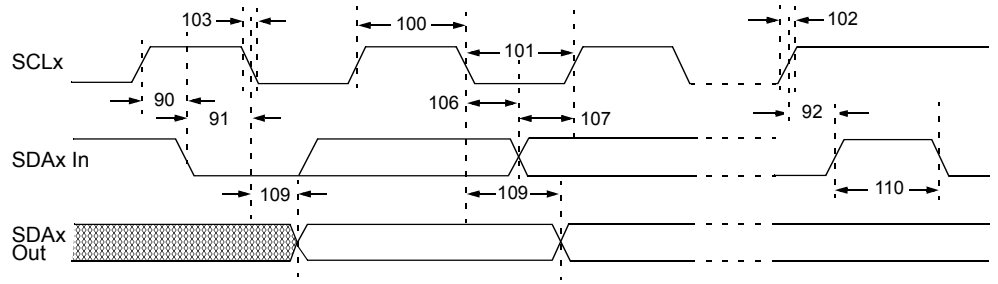


Note: Refer to Figure 27-5 for load conditions.

TABLE 27-29: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 0)

Param No.	Symbol	Characteristic	Min	Max	Units	Conditions
73	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	20	—	ns	
74	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	40	—	ns	
75	TDOR	SDOx Data Output Rise Time	—	25	ns	
76	TDOF	SDOx Data Output Fall Time	—	25	ns	
78	TSCR	SCKx Output Rise Time (Master mode)	—	25	ns	
79	TSCF	SCKx Output Fall Time (Master mode)	—	25	ns	
	FSCK	SCKx Frequency	—	10	MHz	

FIGURE 27-18: MSSPx I²C™ BUS DATA TIMING



Note: Refer to Figure 27-5 for load conditions.

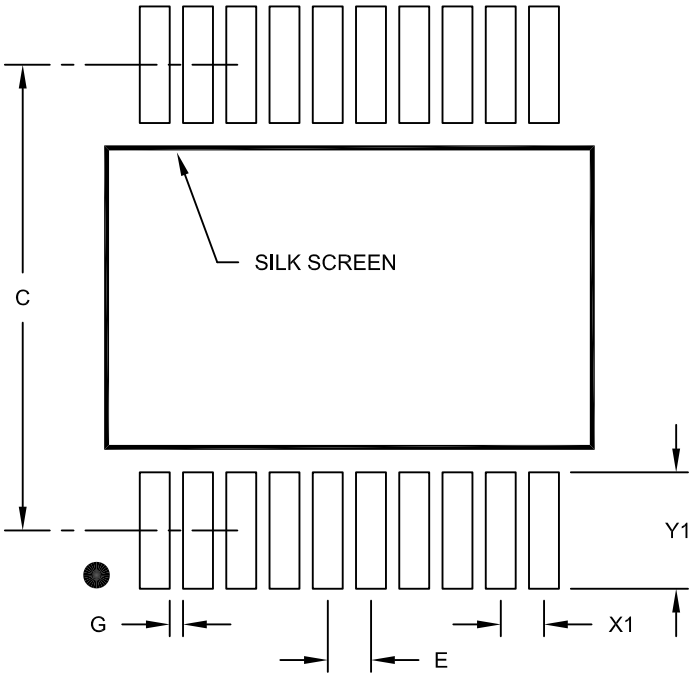
TABLE 27-36: I²C™ BUS DATA REQUIREMENTS (MASTER MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 1)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but Parameter 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, Parameter 102 + Parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCLx line is released.

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2072A

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